

SPECIFICATION FOR APPROVAL

CUSTOMER: _____

PART NO: _____

DESCRIPTION: FHB2012-102-NP

SUBMIT NO: _____

QUANTITY: _____ **PCS**

DATE: _____

| | | |
|-------------------------------------|---------|----------|
| 方瑞达电子（香港）有限公司 | | |
| FONRITA ELECTRONICS (H.K) CO., LTD. | | |
| MADE | CHECKED | APPROVED |
| 张达 | 黎敏 | 邓锋 |

| | | |
|----------------------|---------|----------|
| 贵公司承认栏 | | |
| APPROVED BY MANGEMNT | | |
| MADE | CHECKED | APPROVED |
| | | |



方瑞达电子（香港）有限公司

FONRITA ELECTRONICS (H.K) CO., LIMITED

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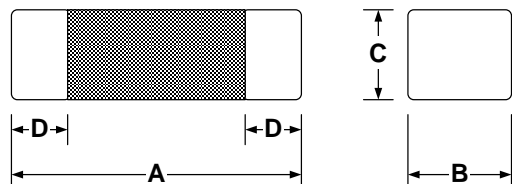
TEL:0755-26617190

FAX:0755-26162625

| | | | |
|-----------------------|-------------------|-------------------|----------------|
| CUSTOMER : | | PART NO. | |
| SPECIFICATIONS | | DATE | |
| PART NAME | DATA SHEET | SPEC(TYPE) | FHB2012-102-NP |

TEST INSTRUMENT

- 1.HP4291A RF IMPEDANCE / MATERIAL ANALYZER FOR Z
- 2.DIGITAL MULTIMETER SC-7401 FOR RDC
- 3.Rated Current (mA)Max. : 300(Thermometer&HP6632A or HP6632A or HP42841A or CH301A)



● **PRODUT IDENTIFICATION:**

FHB 20 12 - 102 - NP
 1 2 3 4 5

- 1.PRONDUCT SYMBOL 2.OUT SIDE DIA:mm
- 3.BODY HEIGHT :mm 4.Normal impedance
- 5.Meet ROHS Regulations of Prohibiped 6 Poisonous Materials

| ELECTRICAL CHARACTERISTICS | | | | DIMENSION | | | |
|----------------------------|--------------------|--------------|--------------|----------------|-----------------|----------------|-----------------|
| ITEM | Z(Ω) | RDC(Ω) | IDC(mA) | A | B | C | D |
| SPEC. | 100MHz 1000±25% | Max. 0.30 | Max. 1000 | m/m 2.0±0.2 | m/m 1.25±0.2 | m/m 0.9±0.2 | m/m 0.5±0.30 |
| 1 | | | | | | | |
| 2 | | | | | | | |
| 3 | | | | | | | |
| 4 | | | | | | | |
| 5 | | | | | | | |
| 6 | | | | | | | |
| 7 | | | | | | | |
| 8 | | | | | | | |
| 9 | | | | | | | |
| 10 | | | | | | | |
| X | | | | | | | |
| R | | | | | | | |
| TEST CONDITION | TEMP: | 25°C | | HUMIDITY: | 50% | | |
| DRAWN BY | | CHECKED BY | | APPROVED BY | | | |
| 张达 | | 黎敏 | | 邓锋 | | | |



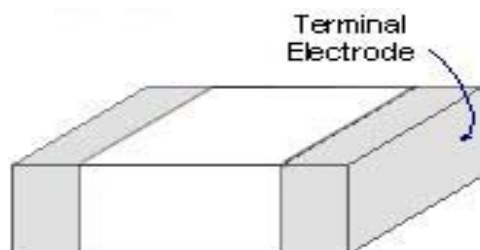
| | | | |
|-----------------------|----------------------|-------------------|----------------|
| CUSTOMER : | | PART NO. | |
| SPECIFICATIONS | | DATE | |
| PART NAME | MATERIAL LIST | SPEC(TYPE) | FHB2012-102-NP |

■ Rating:

Operating Temperature: -55°C~125°C

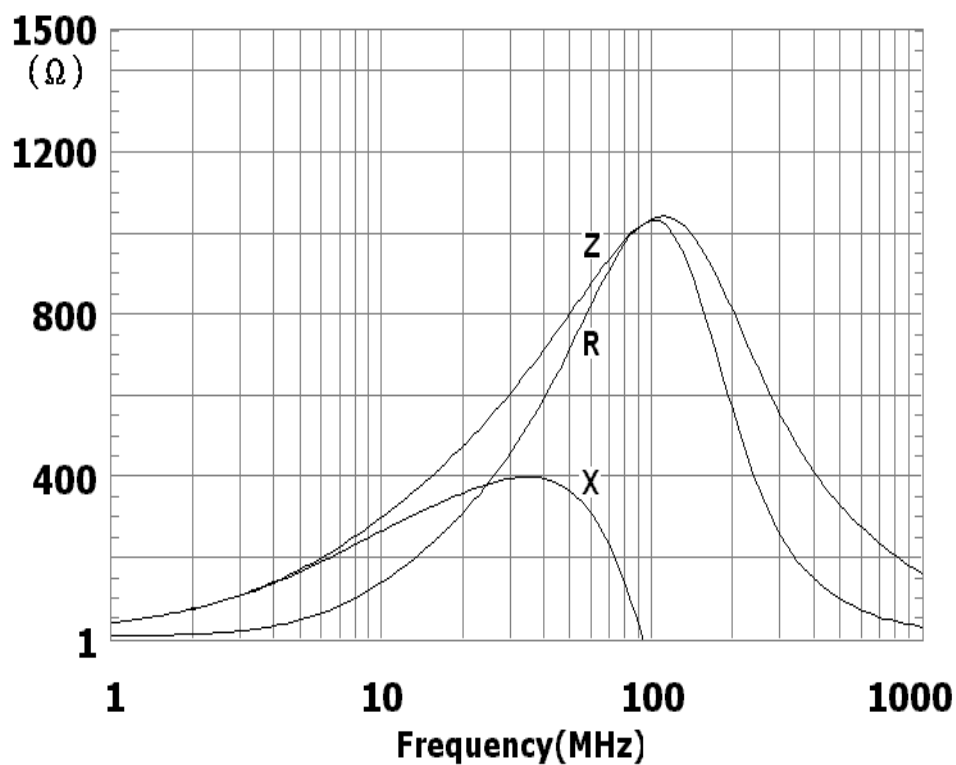
Storage Temperature: -25°C~85°C

■ Marking:



■ Specification

Impedance-Frequency Characteristics

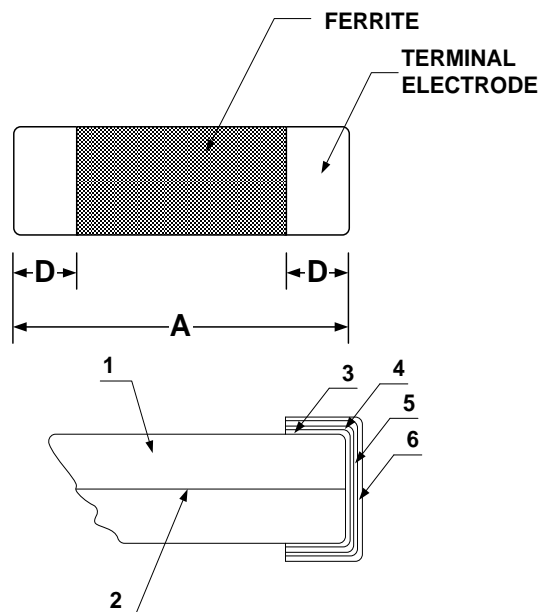


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| | | | |
|-----------------------|-----------------------------|-------------------|----------------|
| CUSTOMER : | | PART NO. | |
| SPECIFICATIONS | | DATE | |
| PART NAME | Series Specification | SPEC(TYPE) | FHB2012-102-NP |

■ Construction:



| NO | PART | MATERLAL |
|----|-------------------|---------------------|
| 1 | Ferrite Substance | NiO-CuO-ZnO-Ferrite |
| 2 | Silver electrode | Ag |
| 3 | Silver electrode | Ag |
| 4 | Cu plating | Cu |
| 5 | Ni plating | Ni |
| 6 | Sn plating | Sn |

■ Standard Testing Condition

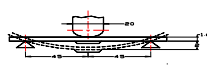
| | Unless otherwise specified | In case of doubt |
|-------------|----------------------------------|------------------|
| Temperature | Ordinary Temperature(15 to 35°C) | 20±2°C |
| Humidity | Ordinary Humidity(25 to 85% RH) | 60 to 70 % RH |



| | | | |
|-----------------------|----------------------|-------------------|----------------|
| CUSTOMER : | | PART NO. | |
| SPECIFICATIONS | | DATE | |
| PART NAME | MATERIAL LIST | SPEC(TYPE) | FHB2012-102-NP |

■ Reliability of Chip Beads (FHB SERIES)

1.Mechanical Performance

| NO | Item | Specification | Test Method |
|----|------------------------------|--|--|
| 1 | Flexure Strength | Appearance :No damage L change :within±10% Q change :within±30% | Test device shall be soldered on the substrate Substrate Dimension:100*40*1.6mm Deflection:2.0mm Keeping Time:30sec For 100505,substratedimension is 100*40*0.8mm  |
| 2 | Vibration | | Test device shall be soldered on the substrate Oscillation Frequency : 10 to 55to 10Hz for Amplitude : 1.5mm Time : 2hrs for each axis (X , Y & Z), TOTAL |
| 3 | Resistance to Soldering Heat | Appearance :No damage More than 75% of the terminal Electrode should be covered with solder. Impedance: with in ±15% of initial value. Q: within±30%of initial value | Pre-heating: 150°C , 1min Solder Composition: Sn/3.0Ag/0.5Cu Solder Temperature:260±5°C Immersion Time:10±1SEC Measured after exposure in the room condition for 24hrs |
| 4 | Solderability | The electrodes shall be at least 90% covered with new solder coating | Pre-heating : 150°C,1min Solder Composition :Sn / Pn =63/37 Solder Temperature :230±5°C Immersion Time :4±1sec |



| | | | |
|-----------------------|----------------------|-------------------|----------------|
| CUSTOMER : | | PART NO. | |
| SPECIFICATIONS | | DATE | |
| PART NAME | MATERIAL LIST | SPEC(TYPE) | FHB2012-102-NP |

■ Reliability of Chip Beads (FHB SERIES)
Environmental Performance

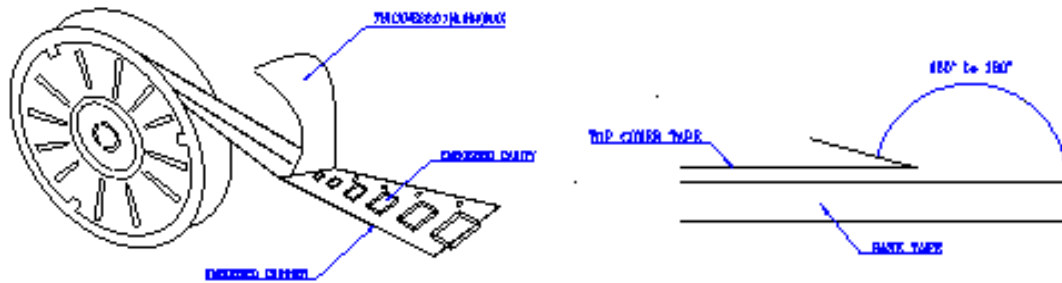
| NO | Item | Specification | Test Method | | |
|----|-----------------------------|--|---|------------------|-----------|
| 1 | Temperature Cycle | Appearance : No damage | Once cycle: | | |
| | | L change : within±10% | Step | Temperature (°C) | Time(min) |
| | | Q change : within±30% | 1 | -25±3 | 30 |
| | | | 2 | 25±2 | 3 |
| | | | 3 | 85±3 | 30 |
| | | | 4 | 25±2 | 3 |
| | | Total:100chcles Measured after exposure in the room condition for 24hrs | | | |
| 2 | Humidity Resistance | | Temperature :40±2°C Relative Humidity : 90~95% Time : 1000hrs Measured after exposure in the room condition for 24hrs | | |
| 3 | Heat Temperature Resistance | | Temperature :85±3°C Relative Humidity :20% Applied Current: Rated Current Time :1000hrs Measured after exposure in the room condition for 24hrs | | |
| 4 | Low Temperature Resistance | | Temperature :-25±3°C Relative Humidity:0% Time : 1000hrs Measured after exposure in the room condition for 24hrs | | |



| | | | |
|-----------------------|---------------------------|-------------------|----------------|
| CUSTOMER : | | PART NO. | |
| SPECIFICATIONS | | DATE | |
| PART NAME | CARRIER & REEL | SPEC(TYPE) | FHB2012-102-NP |

■ **PACKAGING**

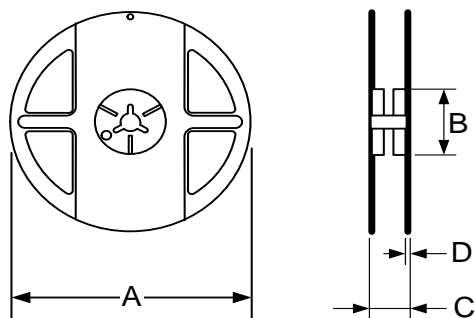
Packaging – Cover tape



Packaging Quantity

| TYPE | BULK | PCS/REEL |
|----------|------|----------|
| FHB-2012 | ✓ | 4000 |

■ **REEL DIMENSION :m/m**



| TYPE | A | B | C |
|----------|-----|----|----|
| FHB-2012 | 178 | 60 | 12 |



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